

REMARKS

Claims 1-13 remain in the application for consideration of the Examiner.

Reconsideration and withdrawal of the outstanding rejections are respectfully requested in light of the following remarks.

Turning now to the art rejections, Claims 1-4, 6-10, 12, and 13 were rejected under 35 U.S.C. § 103 as being unpatentable over alleged admitted prior art (AAPA) in view Distefano, Maggio, Gurevich, or Quirke; and Claims 4 and 10 were rejected under 35 U.S.C. § 103 as being unpatentable over AAPA in view of Distefano, Maggio, Gurevich, Quirke and further in view of Hembree or Hashish.

It is respectfully submitted that AAPA does not disclose or suggest the presently claimed invention including the step of cutting through the integrated circuit package to be singulated with a water jet to access an interior portion of the integrated circuit package in independent Claim 1, albeit defined as pressurizing the water jet such that the water jet is operable to cut through the integrated circuit package to access the interior portion of the integrated circuit package to be singulated in independent Claim 8.

As part of the detailed description of the invention discloses cross sectioning is such that integrated circuit package is cut such at an interior portion of the integrated package is accessible for testing the singulation process is performed with a diamond blade saw.

The diamond blade saw results in many problems, such as high tooling costs, higher mechanical and thermal deformities of integrated circuit package, and less dimensional precision and accuracy.

In contrast, the present invention utilizes a water jet machining system as such solves the problem of cutting through an interior portion of the integrated circuit package.

Distefano does not disclose or suggest the presently claimed invention including the step of cutting through the integrated circuit package to be singulated with a water jet to access an interior portion of the integrated circuit package.

The Examiner alleges that substituting a water jet for other methods of cutting electronic packages is known in the art.

However, cutting the interior portion of the integrated circuit package with a water jet is not known.

Furthermore, Applicants have shown an unexpected advantage in lower tooling costs, lower mechanical and thermal deformations of the integrated circuit package, increased dimensional precision, and accuracy as a result of cutting through the integrated circuit package to access the interior portion of the integrated circuit package with a water jet.

Maggio, Gurevich, Quirke, Distefano, Hashish, Hembree, or Romanini do not cure the above noted defects.

Furthermore, the Examiner alleges that it would have been obvious to one of ordinary skill in the art to provide a water jet of AAPA with pressure to retain approximately 50 and 2500 psi.

Applicants request a teaching from the prior art.

In light of the above, it is respectfully submitted that the present application is in condition for allowance, and notice to that effect is respectfully requested.

While it is believed that the instant amendment places the application in condition for allowance, should the Examiner have any further comments or suggestions, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicant petitions for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



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